

GaAlAs-Lumineszenzdiode (660 nm)
GaAlAs Light Emitting Diode (660 nm)
Lead (Pb) Free Product - RoHS Compliant
SFH 4860



Wesentliche Merkmale

- Hergestellt im Schmelzepitaxieverfahren
- Kathode galvanisch mit dem Gehäuseboden verbunden
- Hohe Zuverlässigkeit
- Gute spektrale Anpassung an Si-Fotoempfänger
- Hermetisch dichtes Metallgehäuse

Anwendungen

- Lichtschranken für Gleich- und Wechsellichtbetrieb
- IR-Gerätefernsteuerungen
- Sensorik
- Lichtgitter

Features

- Fabricated in a liquid phase epitaxy process
- Cathode is electrically connected to the case
- High reliability
- Matches all Si-Photodetectors
- Hermetically sealed package

Applications

- Photointerrupters
- IR remote control
- Sensor technology
- Light curtains

| Typ Type | Bestellnummer Ordering Code | Gehäuse Package |
|-------------|--------------------------------|--|
| SFH 4860 | Q62702P5053 | 18 A3 DIN 41876 (TO-18), Bodenplatte, Plankappe, Anschlüsse im 2.54-mm-Raster ($\frac{1}{10}$ ") Anodenkennzeichnung: Nase am Gehäuseboden 18 A3 DIN 870 (TO-18), flat glass cap, lead spacing 2.54 mm ($\frac{1}{10}$ ") anode marking: projection at package bottom |

Grenzwerte ($T_A = 25^\circ\text{C}$)**Maximum Ratings**

| Bezeichnung Parameter | Symbol Symbol | Wert Value | Einheit Unit |
|--|--------------------------|----------------|-----------------|
| Betriebs- und Lagertemperatur Operating and storage temperature range | $T_{op}; T_{stg}$ | - 40 ... + 100 | °C |
| Sperrsichttemperatur Junction temperature | T_j | 125 | °C |
| Sperrspannung Reverse voltage | V_R | 3 | V |
| Durchlassstrom Forward current | I_F | 50 | mA |
| Stoßstrom, $t_p = 10 \mu\text{s}, D = 0$ Surge current | I_{FSM} | 1 | A |
| Verlustleistung Power dissipation | P_{tot} | 140 | mW |
| Wärmewiderstand Thermal resistance | R_{thJA} R_{thJC} | 450 160 | K/W K/W |

Kennwerte ($T_A = 25^\circ\text{C}$)**Characteristics**

| Bezeichnung Parameter | Symbol Symbol | Wert Value | Einheit Unit |
|---|------------------------------|----------------------|-----------------|
| Wellenlänge der Strahlung Wavelength at peak emission $I_F = 50 \text{ mA}$ | λ_{peak} | 660 | nm |
| Spektrale Bandbreite bei 50% von I_{max} Spectral bandwidth at 50% of I_{max} $I_F = 50 \text{ mA}$ | $\Delta\lambda$ | 25 | nm |
| Abstrahlwinkel Half angle | ϕ | ± 50 | Grad deg. |
| Aktive Chipfläche Active chip area | A | 0.106 | mm^2 |
| Abmessungen der aktiven Chipfläche Dimension of the active chip area | $L \times B$ $L \times W$ | 0.325×0.325 | mm^2 |
| Schaltzeiten, I_e von 10% auf 90% und von 90% auf 10%, bei $I_F = 50 \text{ mA}$, $R_L = 50 \Omega$ Switching times, I_e from 10% to 90% and from 90% to 10%, $I_F = 50 \text{ mA}$, $R_L = 50 \Omega$ | t_r, t_f | 100 | ns |

Kennwerte ($T_A = 25^\circ\text{C}$)**Characteristics (cont'd)**

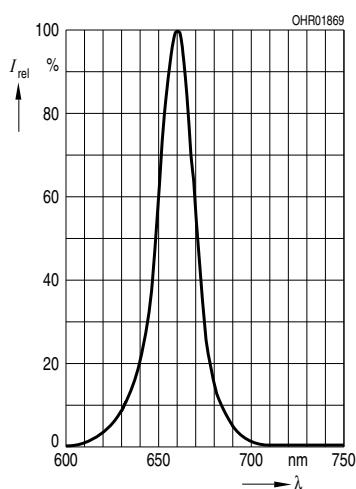
| Bezeichnung Parameter | Symbol Symbol | Wert Value | Einheit Unit |
|---|--------------------------|-----------------------|-------------------------|
| Kapazität, $V_R = 0 \text{ V}, f = 1 \text{ MHz}$ Capacitance | C_o | 25 | pF |
| Durchlassspannung, $I_F = 50 \text{ mA}, t_p = 20 \text{ ms}$ Forward voltage | V_F | 2(≤ 2.8) | V |
| Sperrstrom, $V_R = 3\text{V}$ Reverse current | I_R | 0.01 (≤ 10) | μA |
| Gesamtstrahlungsfluss, $I_F = 50\text{mA}, t_p = 20 \text{ ms}$ Total radiant flux | Φ_e | 3 | mW |
| Temperaturkoeffizient von I_e bzw. Φ_e , $I_F = 50 \text{ mA}$ Temperature coefficient of I_e or Φ_e , $I_F = 50 \text{ mA}$ | TC_I | - 0.4 | %/K |
| Temperaturkoeffizient von $V_F, I_F = 50 \text{ mA}$ Temperature coefficient of $V_F, I_F = 50 \text{ mA}$ | TC_V | - 3 | mV/K |
| Temperaturkoeffizient von $\lambda, I_F = 50 \text{ mA}$ Temperature coefficient of $\lambda, I_F = 50 \text{ mA}$ | TC_λ | + 0.16 | nm/K |

Strahlstärke I_e in Achsrichtunggemessen bei einem Raumwinkel $\Omega = 0.01 \text{ sr}$ **Radiant Intensity I_e in Axial Direction**at a solid angle of $\Omega = 0.01 \text{ sr}$

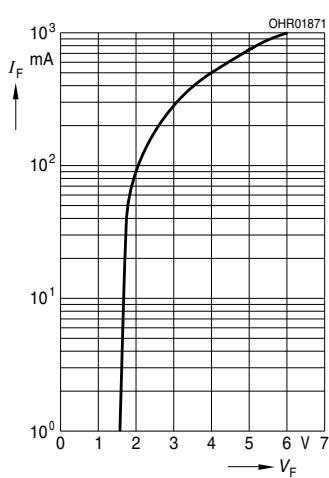
| Bezeichnung Parameter | Symbol | Werte Values | Einheit Unit |
|---|-------------------------------------|-------------------------|-------------------------|
| Strahlstärke Radiant intensity $I_F = 50 \text{ mA}, t_p = 20 \text{ ms}$ | $I_{e \min}$ $I_{e \text{ typ}}$ | ≥ 0.63 1.3 | mW/sr mW/sr |
| Strahlstärke Radiant intensity $I_F = 1 \text{ A}, t_p = 100 \mu\text{s}$ | $I_{e \text{ typ}}$ | 15 | mW/sr |

Relative Spectral Emission

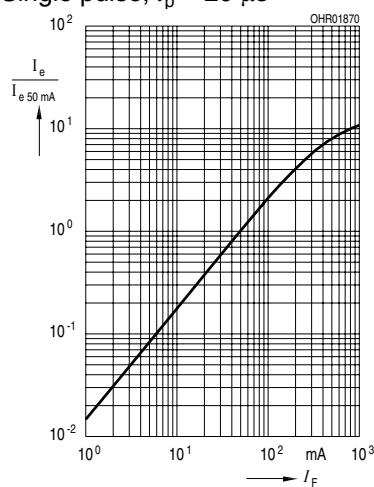
$$I_{\text{rel}} = f(\lambda)$$

**Forward Current**

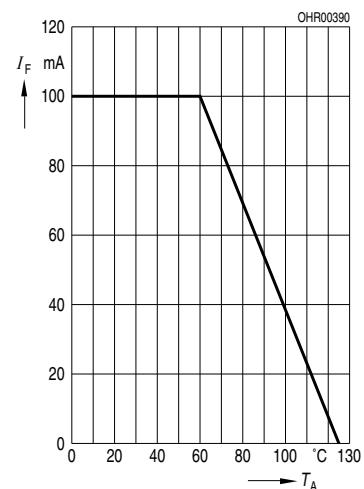
$$I_F = f(V_F), \text{ single pulse, } t_p = 20 \mu\text{s}$$

**Radiant Intensity** $\frac{I_e}{I_{e, 50 \text{ mA}}} = f(I_F)$

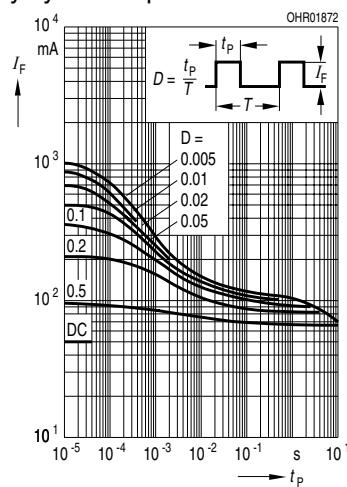
Single pulse, $t_p = 20 \mu\text{s}$

**Max. Permissible Forward Current**

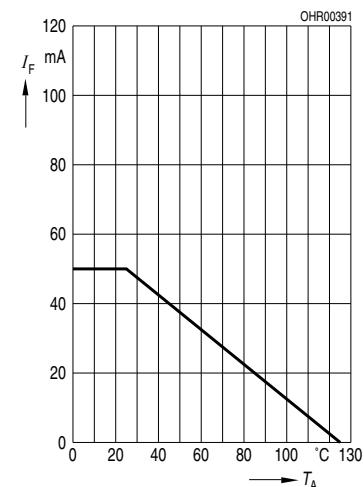
$$I_F = f(T_A), R_{\text{thJC}} = 160 \text{ K/W}$$

**Permissible Pulse Handling Capability**

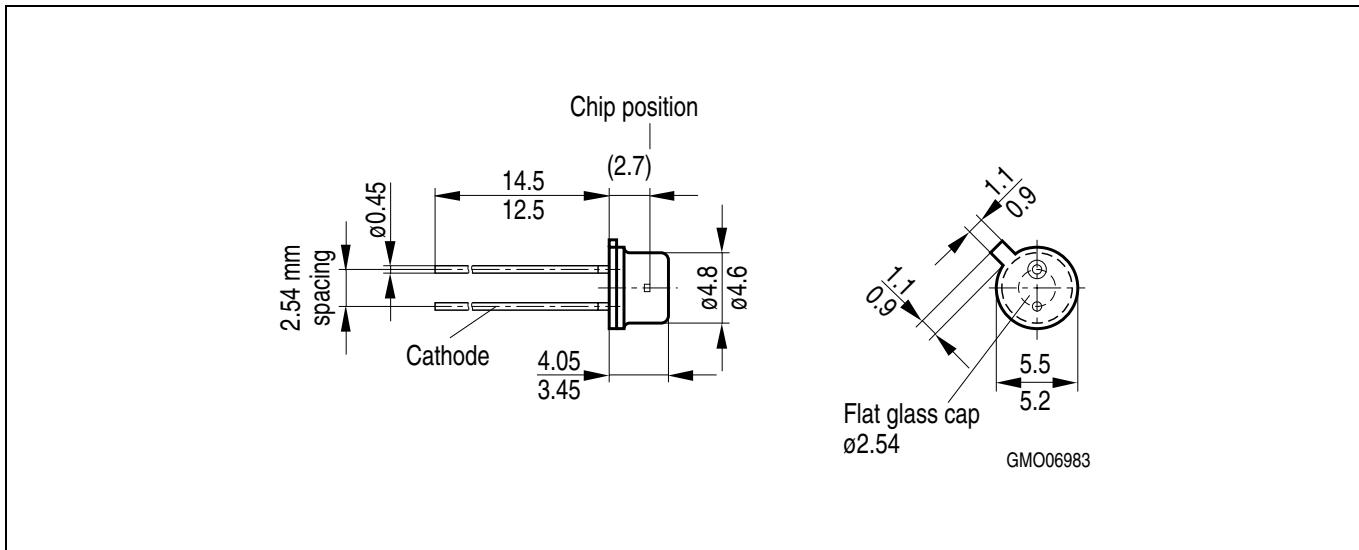
$$I_F = f(\tau), T_A = 25^\circ\text{C}, \text{duty cycle } D = \text{parameter}$$

**Max. Permissible Forward Current**

$$I_F = f(T_A), R_{\text{thJA}} = 450 \text{ K/W}$$



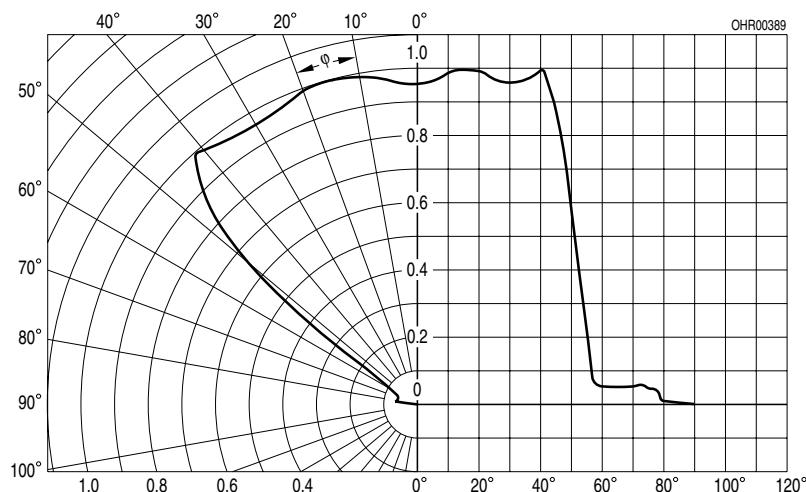
Maßzeichnung Package Outlines



Maße in mm (inch) / Dimensions in mm (inch).

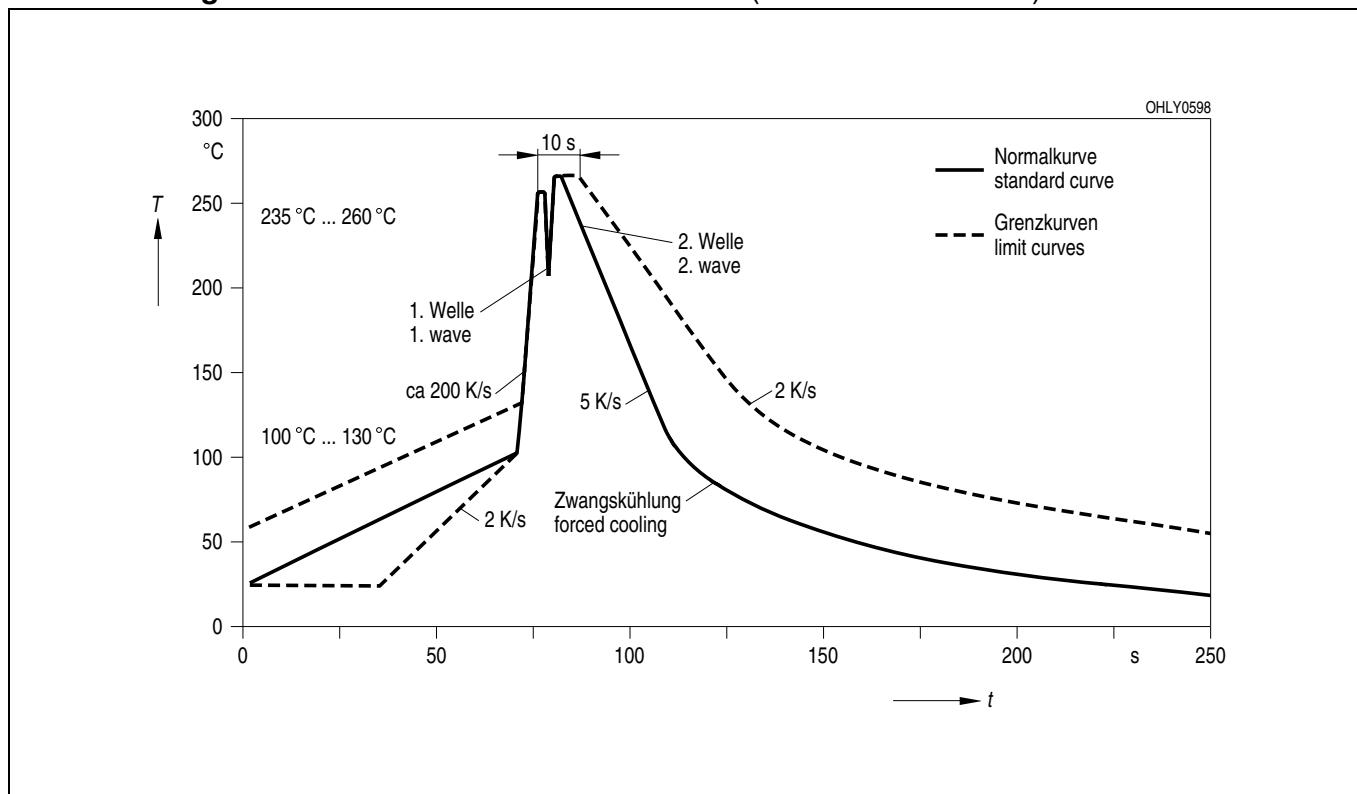
Radiation Characteristics

$$I_{\text{rel}} = f(\phi)$$



Lötbedingungen
Soldering Conditions
Wellenlöten (TTW)
TTW Soldering

(nach CECC 00802)
 (acc. to CECC 00802)



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